

/ Descriptions

SOT-523 P MOS

P-CHANNEL MOSFET in a SOT-523 Plastic Package.

/ Features

 $V_{DS}(V) = -20\text{ V}$ $I_D = -0.7\text{ A}$ $R_{DS(ON)}@-4.5\text{ V} \leq 520\text{ m}\Omega$ (Typ. 400m Ω) $R_{DS(ON)}@-2.5\text{ V} \leq 780\text{ m}\Omega$ (Typ. 570m Ω) $R_{DS(ON)}@-1.8\text{ V} \leq 1100\text{ m}\Omega$ (Typ. 810m Ω)

2KV ESD protected up to 2KV.

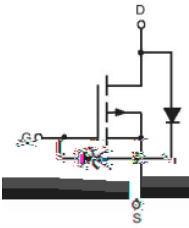
HF Product.

/ Applications

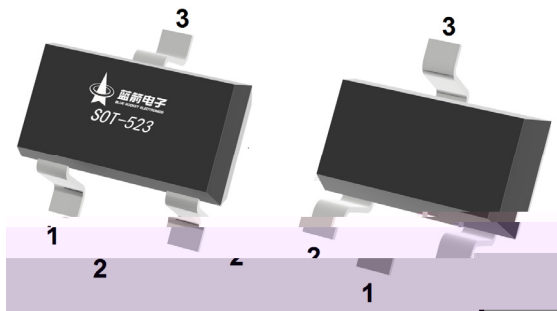
DC/DC

Load Switching, Low Current Inverters, Low Current DC/DC Converters.

/ Equivalent Circuit



/ Pinning



PIN1 G

PIN 2 S

PIN 3 D

/ Marking

See Marking Instructions.

/ Electrical Characteristic Curve

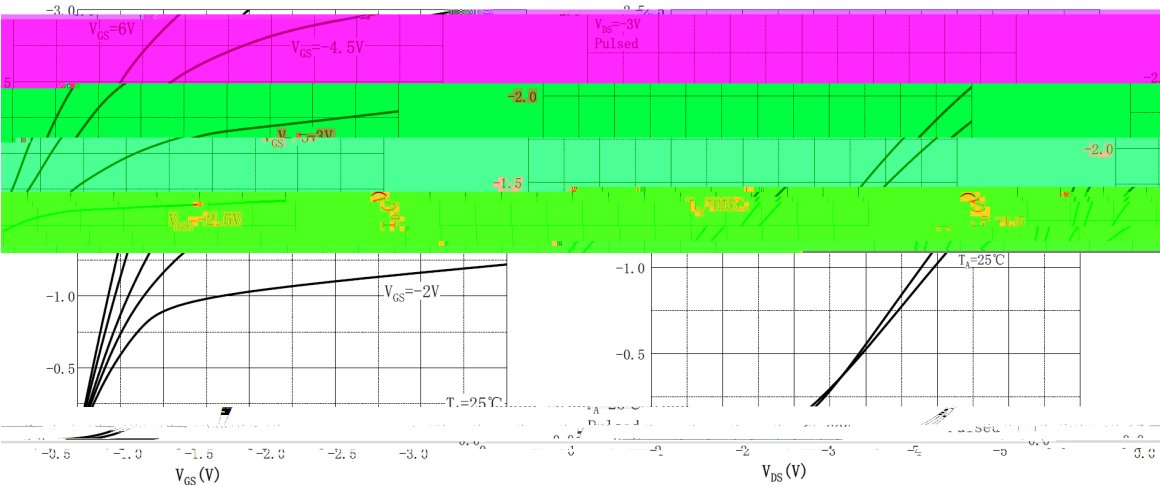


Figure 1. Output Characteristics

Figure 2. Transfer Characteristics

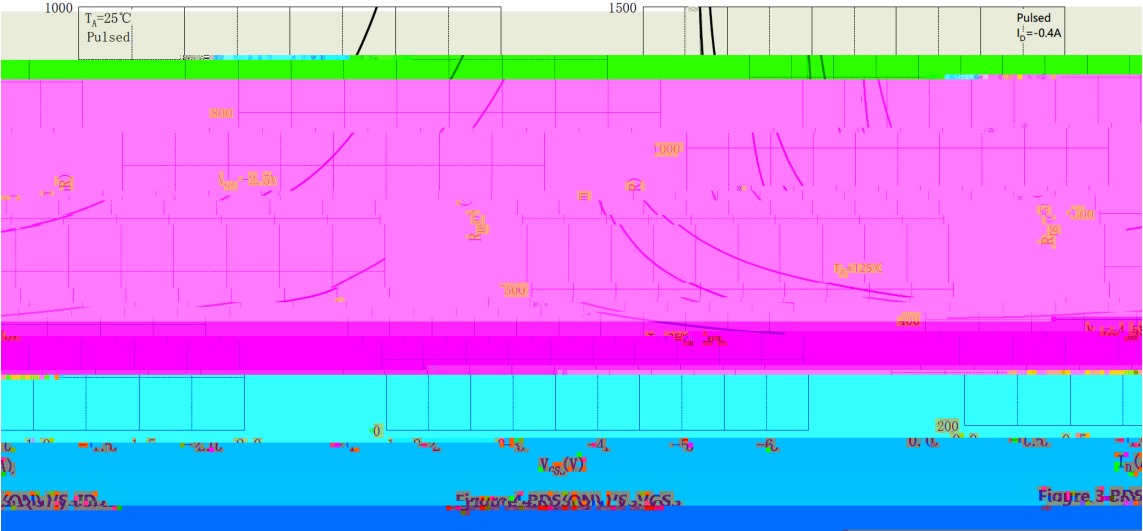
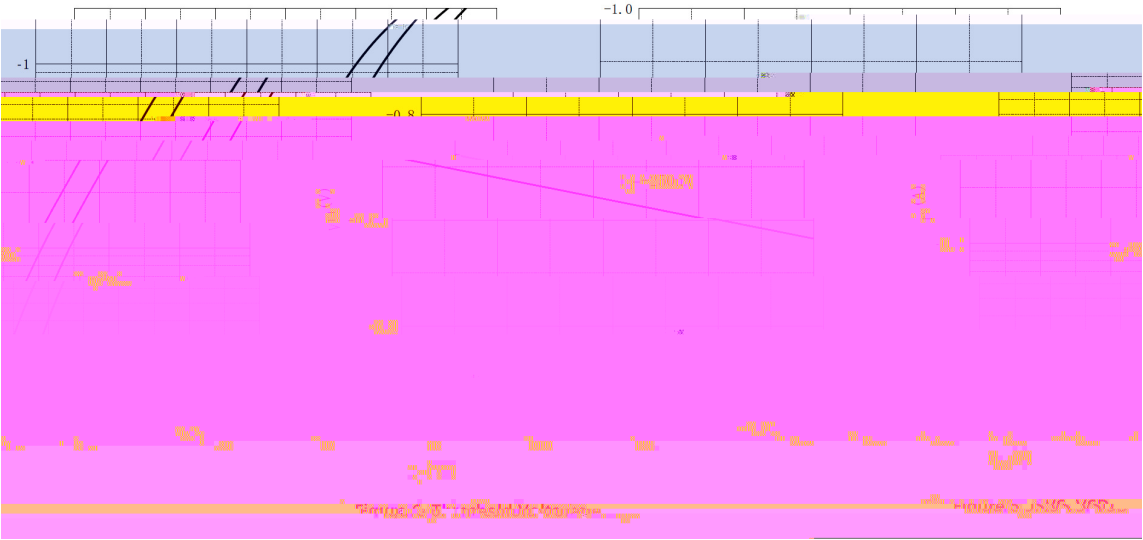
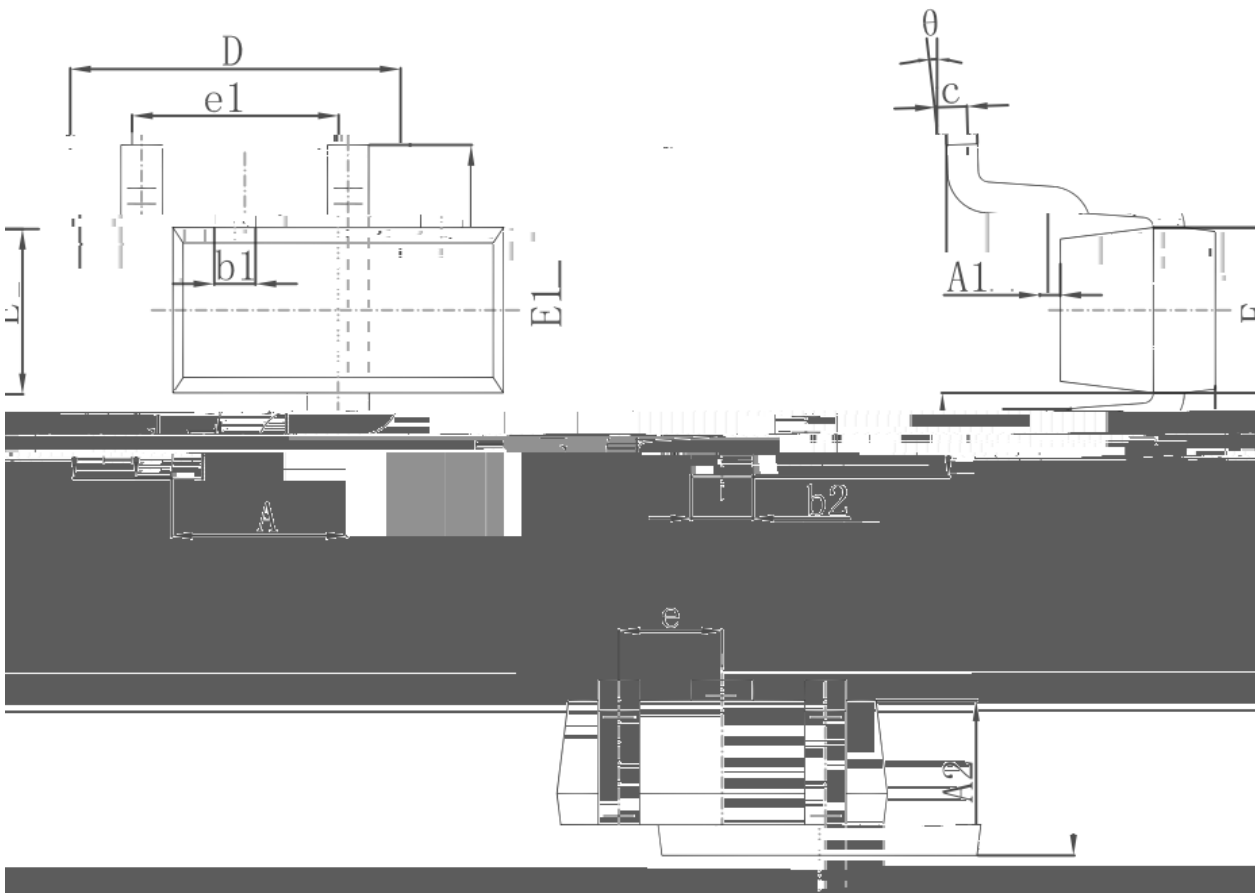


Figure 3. Transfer Characteristics

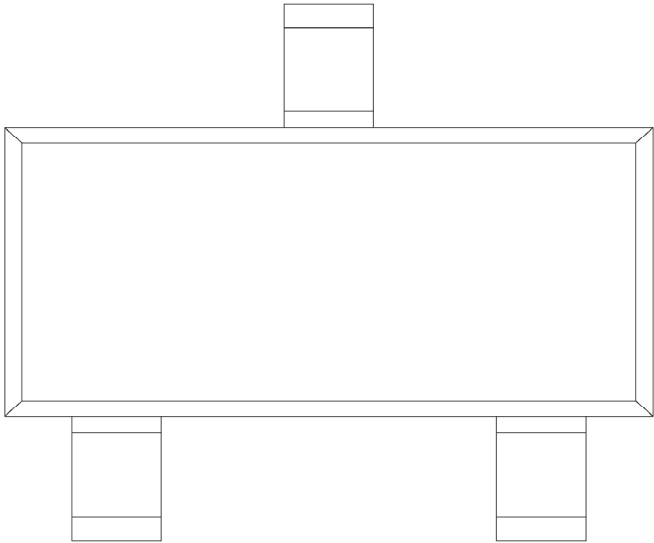


/ Package Dimensions



Dimensions In Inches		Symbol		Dimensions In Millimeters	
Min.	Max.			Min.	Max.
0.028	0.035	A		0.700	0.900
0.000	0.004	A1		0.000	0.100
0.028	0.031	A2		0.700	0.800
0.200	0.250	b2		0.008	0.010
0.000	0.004	c		0.008	0.010
1.500	1.700	D		0.067	0.067
0.700	0.900	e1		0.028	0.035
0.057	0.069	L		1.450	1.700
0.020 TYP.		L1		0.500 TYP.	
0.035		θ		0.900	
0.016 REF.				0.400 REF.	
0.010	0.018			0.260	0.400
0°				0°	

/ Marking Instructions



39K

() / Temperature Profile for IR Reflow Soldering(Pb-Free)

- Note:
- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.

2

245±5

5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.

3

2 10

/sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box